

LINEAR TECHNOLOGY MATERIALS DECLARATION

1tc3897huhg-2#pbf

(Engineering Calculation)

QFN 5mm X 8mm Exp. Pad

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TOTAL MASS (g) : 0.004919

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.	
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003226	1000000	655824.375	
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0	
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.000000	0	0	
		Iron (Fe)	7439-89-6	0.000000	0	0	
		Phosphorus (P)	7723-14-0	0.000000	0	0	
		Zinc (Zn)	7440-66-6	0.000000	0	0	
		Nickel (Ni)	7440-02-0	0.000000	0	0	
		Silicon (Si)	7440-21-3	0.000000	0	0	
		Magnesium (Mg)	7439-95-4	0.000000	0	0	
		Tin (Sn)	7440-31-5	0.000000	0	0	
Lead Frame Total:				0.000000	0	0	
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0	
		Exter. Plating Sn	7440-31-5	0.000000	1000000	0	
		External Plating Total:				0.000000	0
		Inter. Plating Ni	7440-02-0	0.000000	0	0	
		Inter. Plating Ag	7440-22-4	0.000000	0	0	
Internal Plating Total:				0.000000	0		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001270	750000	258182.5625	
		Tin (Sn)	7440-31-5	0.000000	0	0	
		Lead (Pb)	7439-92-1	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	0	0	
		Indium (In)	7440-74-6	0.000000	0	0	
		Metal Oxide		0.000000	0	0	
		Antimony (Sb)	7440-36-0	0.000000	0	0	
		Resin (EP)		0.000423	250000	85993.0859375	
Die Attach Total:				0.001693	1000000	344175.625	
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.000000	130000	0	
		Bromine (Br)	40039-93-8	0.000000	0	0	
		Silica (SiO2)	60676-86-0	0.000000	860000	0	
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0	
		Metal Hydroxide		0.000000	0	0	
		Carbon Black (C)	1333-86-4	0.000000	10000	0	
		Encapsulation Total:				0.000000	1000000
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000000	0	0	
					TOTAL MASS (g) :	0.004919	